Ceramic Plate Series CP12-161-06-L1-EP-W12
MFG Part Number: 101161045101

Ceramic Plate Series Thermoelectric Cooler

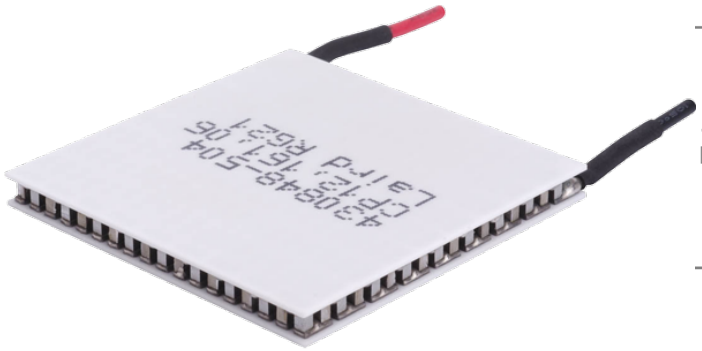
The CP12-161-06-L1-EP-W12 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Qc of 47.7 Watts when ΔT = 0 and a maximum ΔT of 70.5 °C at Qc = 0.

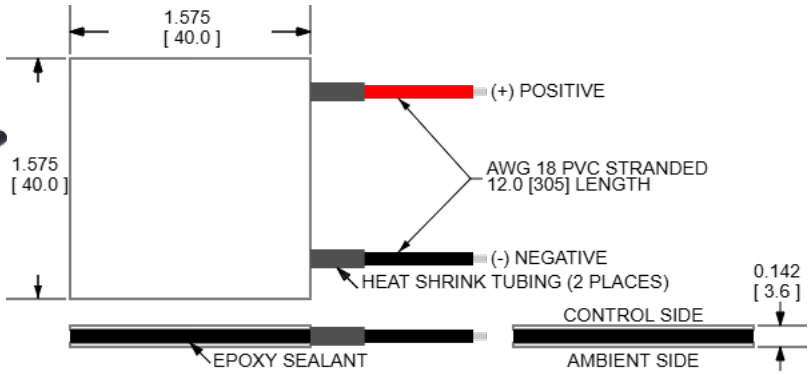
Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Peltier Cooling for Machine Vision

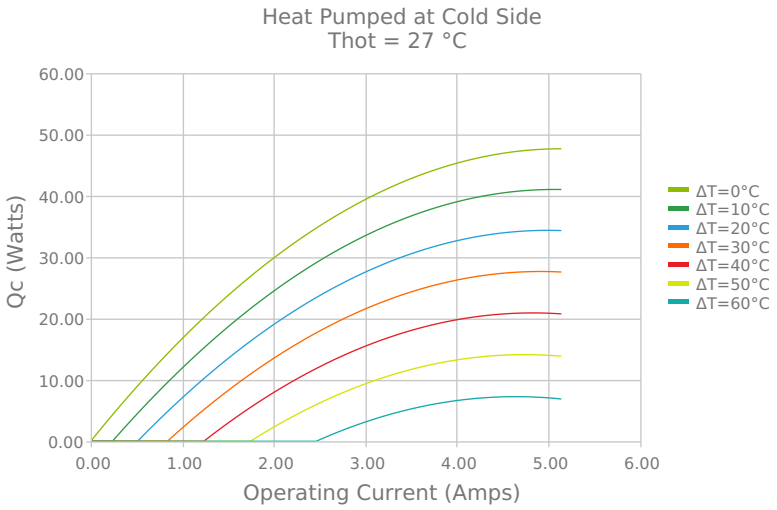


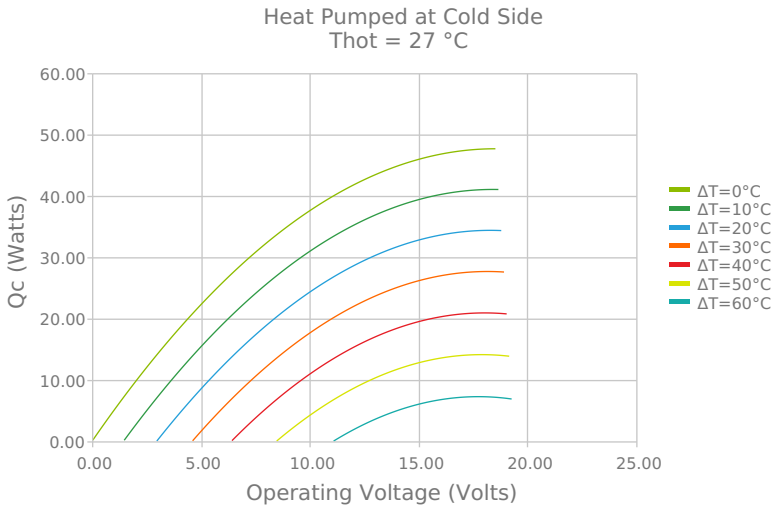


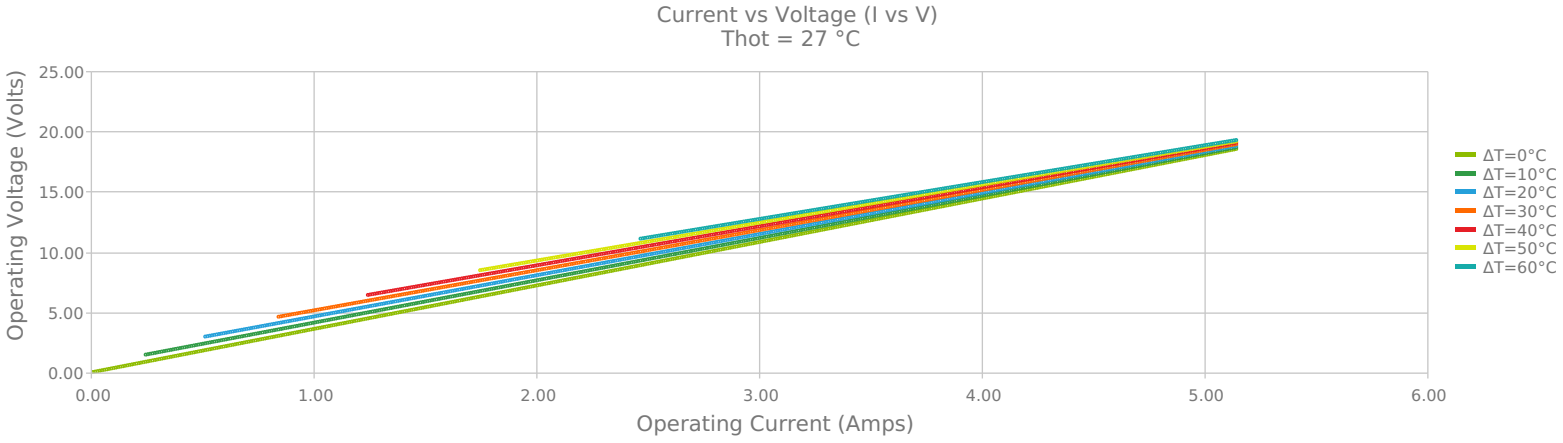
CERAMIC MATERIAL: Al_2O_3
SOLDER CONSTRUCTION: 138°C, BiSn
INCHES [MM]
Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

Electrical and Thermal Performance

For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the AMBIENT side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.







TTS
TARK THERMAL SOLUTIONS

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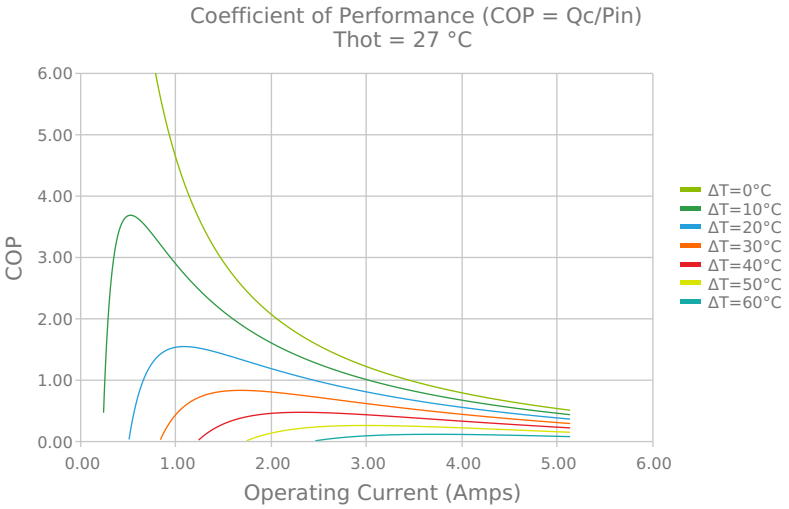

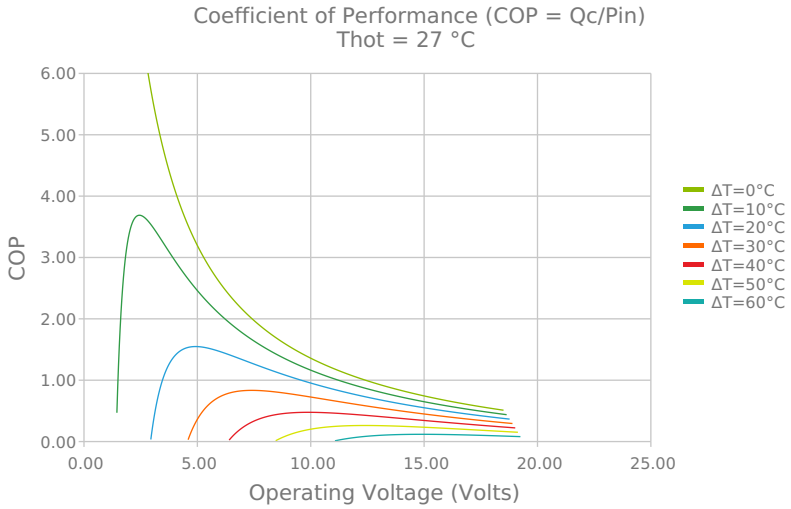

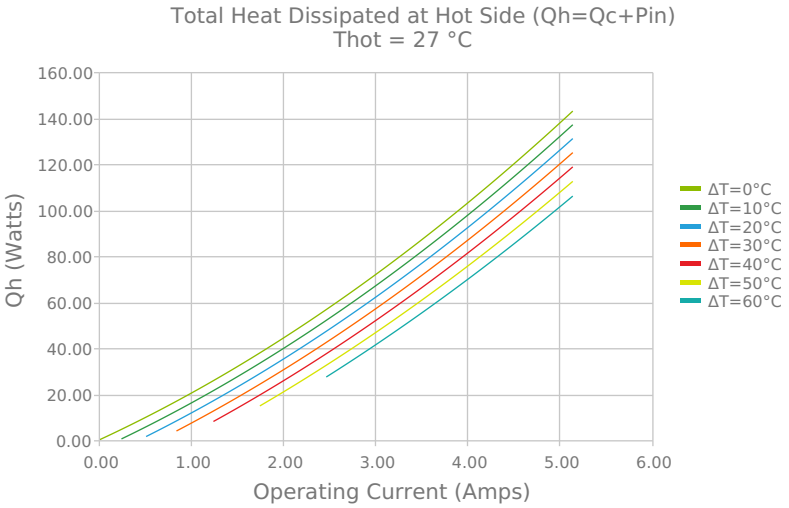

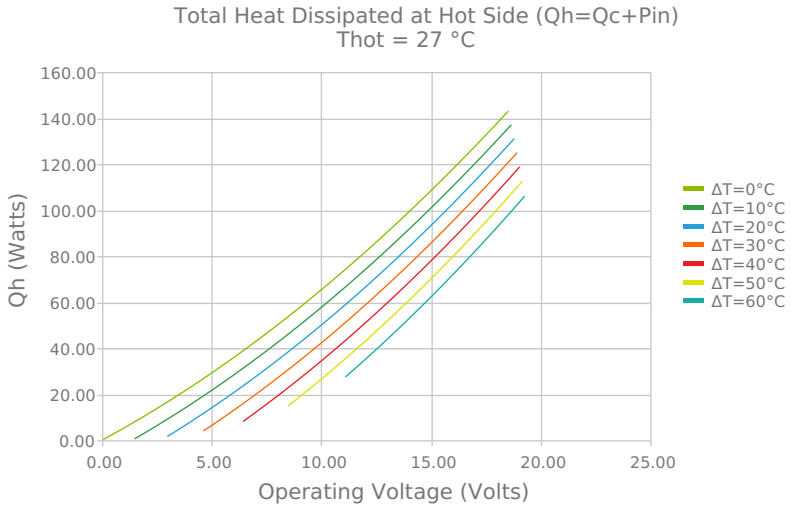

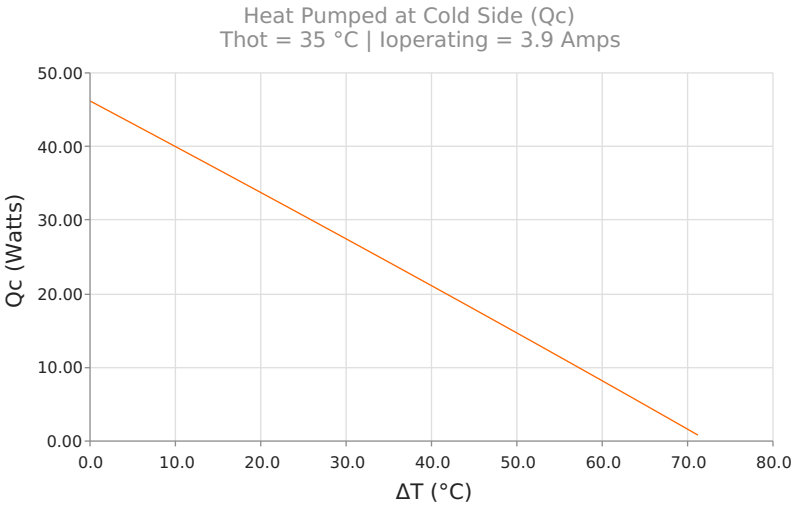

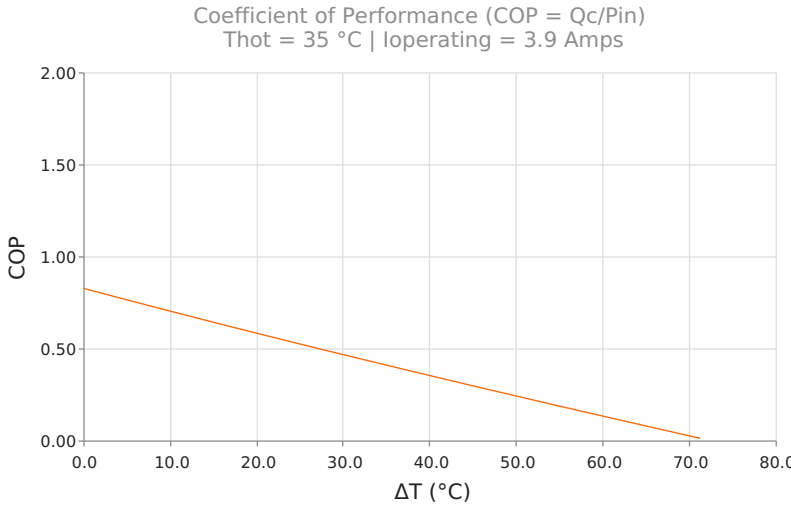

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Specifications

Hot Side Temperature	27.0 °C	35.0 °C	50.0 °C
Qcmax (ΔT = 0)	47.7 Watts	49.1 Watts	51.7 Watts
ΔTmax (Qc = 0)	70.5°C	73.5°C	78.8°C
Imax (I @ ΔTmax)	4.5 Amps	4.5 Amps	4.5 Amps
Vmax (V @ ΔTmax)	17.6 Volts	18.3 Volts	19.5 Volts
Module Resistance	3.60 Ohms	3.75 Ohms	4.03 Ohms
Max Operating Temperature	80 °C		
Weight	19.0 gram(s)		

Finishing Options

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
L1	3.607 ±0.025 mm 0.142 ± 0.0010 in	0.025 mm / 0.025 mm 0.001 in / 0.001 in	Lapped	Lapped	304.8 mm 12.00 in

Sealing Options

Suffix	Sealant	Color	Temp Range	Description
EP	Epoxy	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

Notes

Max operating temperature: 80°C
Do not exceed Imax or Vmax when operating module
Reference assembly guidelines for recommended installation
Solder tinning also available on metallized ceramics

Revision: 01 Date: 06-09-2023

Print Date: 06-03-2025